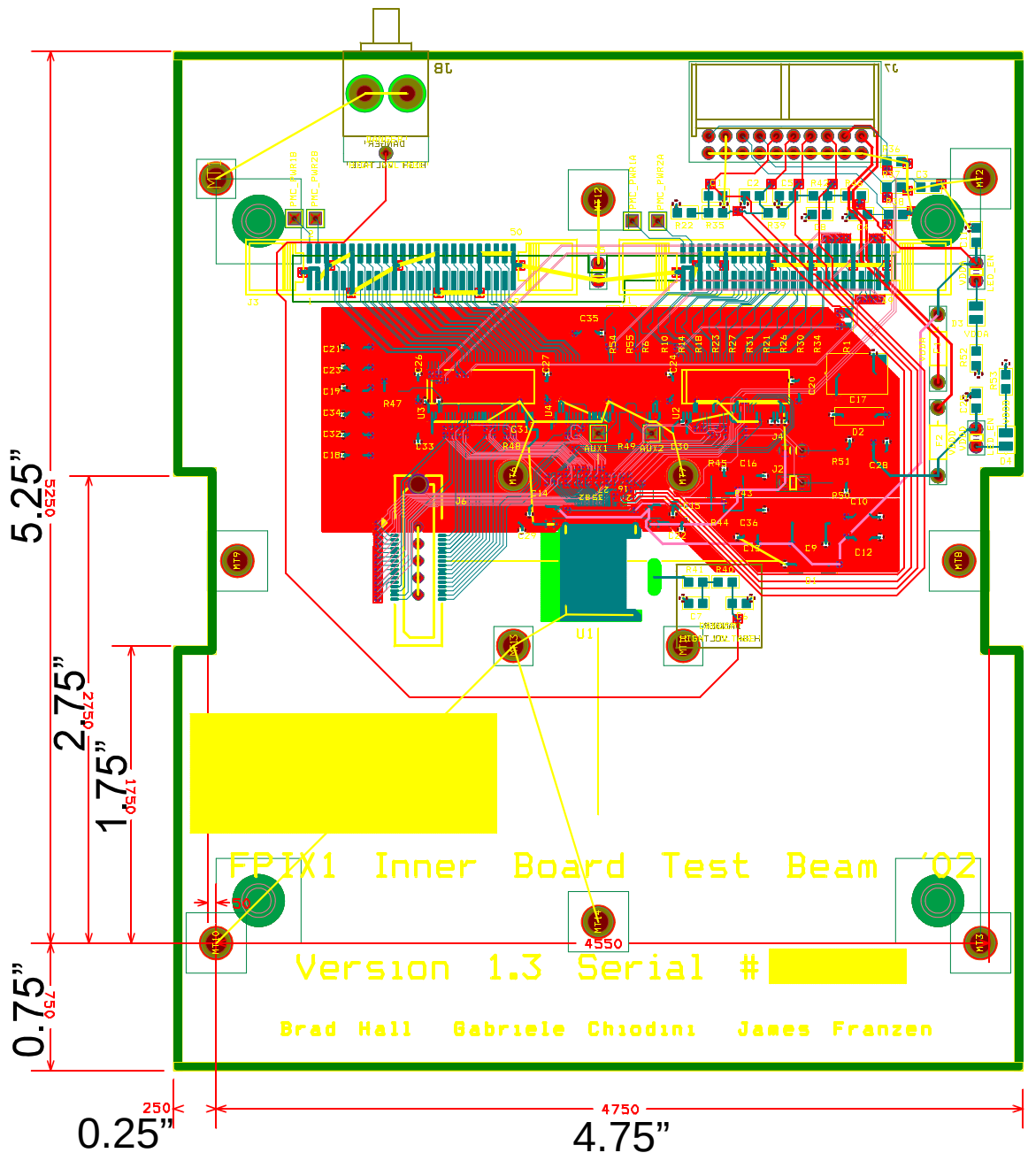

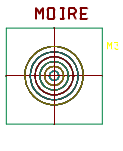

TOP LAYER TO BE GOLD PLATED SUITABLE FOR ALUMINUM WEDGE ULTRASONIC BONDING PROCESS

TOP SURFACE TO EMPLOY 150 MICRO-INCHES OF NICKEL, WITH 7 - 10 MICRO-INCHES OF GOLD OVER THE NICKEL

DRILL CHART				
SYM	DIAM	TOL	QTY	NOTE
⊞	0.012		243	
◇	0.032		5	
×	0.037		6	
⊠	0.038		10	
+	0.040		1	
○	0.042		20	
⌂	0.055		4	
△	0.093		1	
⊗	0.096		2	
⊖	0.125		12	
TOTAL			304	

Version 1.3

4-LAYER STACKUP

FR-4 substrate must have a Tg of 1

BOARD THICKNESS: 0.062" +/-0.003"

ALL LAYERS 1/2oz Cu

Dimensional tolerances +/-0.005"

Internal Radius on corners shall be

1)TOP SIGNAL	1)TOP SIGNAL
2)DGND (PLANE)	2)DGND (PLANE)
3)VCC (PLANE)	3)VCC (PLANE)
4)BOTTOM SIGNAL	4)BOTTOM SIGNAL